

Title (en)

IMPROVED METHOD FOR PRODUCING A LAMINATED LAYER COMPOSITE AND COMPOSITE

Title (de)

VERBESSERTES VERFAHREN ZUR HERSTELLUNG EINES LAMINIERTEN SCHICHTVERBUNDES UND SCHICHTVERBUND

Title (fr)

PROCÉDÉ AMÉLIORÉ DE PRODUCTION D'UN COMPOSITE MULTICOUCHE LAMINÉ ET LAMINÉ

Publication

**EP 2396172 A1 20111221 (DE)**

Application

**EP 10702440 A 20100130**

Priority

- EP 2010000566 W 20100130
- EP 09002025 A 20090213
- EP 10702440 A 20100130

Abstract (en)

[origin: EP2218579A1] The method for the production of a laminated layer composite having a base layer (3) made of thermoplastic polymeric material with a vicat softening temperature and a further layer made of thermoplastic polymeric material, which has a low vicat softening temperature than the thermoplastic polymeric material of the base layer and if necessary a cover layer (5) made of thermoplastic polymeric material, comprises laminating the layer composite at a temperature above vicat softening temperature of the further layer, which has maximum 5[deg] C above the vicat softening temperature of the base layer. The method for the production of a laminated layer composite having a base layer (3) made of thermoplastic polymeric material with a vicat softening temperature and a further layer made of thermoplastic polymeric material, which has a low vicat softening temperature than the thermoplastic polymeric material of the base layer and if necessary a cover layer (5) made of thermoplastic polymeric material, comprises laminating the layer composite at a temperature above the vicat softening temperature of the further layer, which has maximum 5[deg] C above the vicat softening temperature of the base layer, and then laminating at a temperature above the vicat softening temperature of the base layer. A component is contained between the base layer and the further layer. The vicat softening temperature of the further layer is 10[deg] C lower than the vicat softening temperature of the base layer. The component is electronic component or hologram. The electronic component is an integrated circuit, thick film circuits, circuit having discrete active and passive electronic component, sensors, chip module, displays, battery, coils, capacitor, conductor path and/or contact points. The thermoplastic material of the cover layer has a vicat softening temperature, which is higher than the vicat softening temperature of the further layer. An independent claim is included for a laminated layer composite.

IPC 8 full level

**B32B 37/06** (2006.01)

CPC (source: EP)

**B32B 37/06** (2013.01); **B32B 2519/02** (2013.01)

Citation (search report)

See references of WO 2010091796A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

**EP 2218579 A1 20100818**; BR PI1007980 A2 20160301; CA 2752100 A1 20100819; EP 2396172 A1 20111221; TW 201041738 A 20101201; WO 2010091796 A1 20100819

DOCDB simple family (application)

**EP 09002025 A 20090213**; BR PI1007980 A 20100130; CA 2752100 A 20100130; EP 10702440 A 20100130; EP 2010000566 W 20100130; TW 99104536 A 20100212